## - $5-\Omega$ Switch Connection Between Two Ports

## - TTL-Compatible Input Levels

- Designed to Be Used in Level-Shifting Applications
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB, DBQ), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages, Ceramic Flat (W) Package, Ceramic DIPs (JT), and Ceramic Chip Carriers (FK)


## description

The 'CBTD3384 devices provide ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switches allows connections to be made without adding propagation delay. A diode to $\mathrm{V}_{\mathrm{CC}}$ is integrated on the die to allow for level shifting between $5-\mathrm{V}$ inputs and 3.3-V outputs.

These devices are organized as two 5-bit switches with separate output-enable (OE) inputs. When $\overline{\mathrm{OE}}$ is low, the switch is on and port A is connected to port B . When $\overline{\mathrm{OE}}$ is high, the switch is open and a high-impedance state exists between the two ports.
The SN54CBTD3384 is characterized for operation over the full military temperature range from $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$. The SN74CBTD3384 is characterized for operation from $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$.

SN54CBTD3384 ... JT OR W PACKAGE SN74CBTD3384 . . . DB, DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)


SN54CBTD3384... FK PACKAGE (TOP VIEW)


NC - No internal connection

FUNCTION TABLE (each 5-bit bus switch)

| INPUTS |  | INPUTS/OUTPUTS |  |
| :---: | :---: | :---: | :---: |
| 1 $\overline{\mathrm{OE}}$ | 2 $\overline{\mathrm{OE}}$ | 1B1-1B5 | 2B1-2B5 |
| L | L | 1A1-1A5 | 2A1-2A5 |
| L | $H$ | $1 A 1-1 A 5$ | Z |
| $H$ | L | $Z$ | 2A1-2A5 |
| $H$ | $H$ | $Z$ | $Z$ |

## logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, JT, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

> Supply voltage range, $\mathrm{V}_{\mathrm{CC}}$ -0.5 V to 7 V Input voltage range, $\mathrm{V}_{\text {I }}$ (see Note 1) -0.5 V to 7 V
> Continuous channel current 128 mA
> Input clamp current, $\mathrm{I}_{\mathrm{IK}}\left(\mathrm{V}_{\mathrm{I} / \mathrm{O}}<0\right)$. . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . -50 mA
> Package thermal impedance, $\theta_{\text {JA }}$ (see Note 2): DB package . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 104 $\mathrm{C} / \mathrm{W}$
> DBQ package . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . $113^{\circ} \mathrm{C} / \mathrm{W}$
> DGV package ............................................. $139^{\circ} \mathrm{C} / \mathrm{W}$
> DW package . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . $81^{\circ} \mathrm{C} / \mathrm{W}$
> PW package ............................................ $120^{\circ} \mathrm{C} / \mathrm{W}$
> Storage temperature range, $\mathrm{T}_{\text {stg }}$. . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$
> $\dagger$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
> NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
> 2. The package thermal impedance is calculated in accordance with JESD 51.
recommended operating conditions (see Note 3)

|  |  | SN54CBTD3384 |  | SN74CBTD3384 |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | MAX | MIN | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | High-level control input voltage | 2 |  | 2 |  | V |
|  | Low-level control input voltage |  | 0.8 |  | 0.8 | V |
| $\mathrm{T}_{\text {A }}$ | Operating free-air temperature | -55 | 125 | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |

NOTE 3: All unused control inputs of the device must be held at $\mathrm{V}_{\mathrm{C}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER |  | TEST CONDITIONS |  |  | SN54CBTD3384 |  |  | SN74CBTD3384 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYP $\dagger$ | MAX | MIN | TYP $\dagger$ | MAX |  |
| $\mathrm{V}_{\text {IK }}$ |  |  |  |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}, \quad \mathrm{I}=-18 \mathrm{~mA}$ |  |  |  |  | -1.2 |  |  | -1.2 | V |
| $\mathrm{V}_{\mathrm{OH}}$ |  | See Figure 2 |  |  |  |  |  |  |  |  |  |
| 1 |  | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{I}}=5.5$ | GND |  |  | $\pm 1$ |  |  | $\pm 1$ | $\mu \mathrm{A}$ |
| ${ }^{\text {ICC }}$ |  | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | $\mathrm{I} \mathrm{O}=0$, | $\mathrm{V}_{\mathrm{I}}=\mathrm{V}_{\mathrm{CC}}$ or GND |  |  | 1.5 |  |  | 1.5 | mA |
| ${ }^{1} \mathrm{CCC}^{\ddagger}$ | Control inputs | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, One input at 3.4 V , Other inputs at $\mathrm{V}_{\mathrm{CC}}$ or GND |  |  |  |  | 2.5 |  |  | 2.5 | mA |
| $\mathrm{C}_{\mathrm{i}}$ | Control inputs | $\mathrm{V}_{\mathrm{I}}=3 \mathrm{~V}$ or 0 |  |  |  | 3 |  |  | 3 |  | pF |
| $\mathrm{C}_{\mathrm{io}}$ (OFF) |  | $\mathrm{V}_{\mathrm{O}}=3 \mathrm{~V}$ or $0, \quad \overline{\mathrm{OE}}=\mathrm{V}_{\mathrm{CC}}$ |  |  |  | 3.5 |  |  | 3.5 |  | pF |
| $\mathrm{r}_{\mathrm{on}}$ § |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ | $\mathrm{V}_{\mathrm{I}}=0$ | I $=64 \mathrm{~mA}$ |  | 5 |  |  | 5 | 7 | $\Omega$ |
|  |  | $\mathrm{I}=30 \mathrm{~mA}$ |  |  | 5 |  |  | 5 | 7 |  |
|  |  | $\mathrm{V}_{\mathrm{I}}=2.4 \mathrm{~V}, \quad \mathrm{I}=15 \mathrm{~mA}$ |  | 35 |  |  | 35 | 50 |  |

$\dagger$ Typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
$\ddagger$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{C C}$ or GND.
$\S$ Measured by the voltage drop between the $A$ and $B$ terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two ( $A$ or $B$ ) terminals.
switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | $\begin{gathered} \text { TO } \\ \text { (OUTPUT) } \end{gathered}$ | SN54CBTD3384 |  | SN74CBTD3384 |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX |  |
| $t_{p d}{ }^{\text {I }}$ | A or B | B or A |  | 0.25 |  | 0.25 | ns |
| ten | $\overline{\mathrm{OE}}$ | A or B | 2.2 | 9.7 | 2.3 | 7 | ns |
| $\mathrm{t}_{\text {dis }}$ | $\overline{\mathrm{OE}}$ | A or B | 1.5 | 8.6 | 1.7 | 5.3 | ns |

TThe propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION


LOAD CIRCUIT

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

| TEST | S1 |
| :---: | :---: |
| $t_{\text {pd }}$ | Open |
| tPLZ/tPZL | 7 V |
| ${ }_{\text {tPHZ }} /{ }^{\text {P }}$ PZH | Open |


VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES
NOTES:
A. $C_{L}$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 10 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{r}} \leq 2.5 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 2.5 \mathrm{~ns}$.
D. The outputs are measured one at a time with one transition per measurement.
E. $t_{P L Z}$ and $t_{P H Z}$ are the same as $t_{\text {dis }}$.
F. $\mathrm{t}_{\mathrm{P} Z \mathrm{~L}}$ and tPZH are the same as ten.
G. tPLH and tPHL are the same as $t_{\text {pd }}$.

Figure 1. Load Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS



OUTPUT VOLTAGE HIGH
vs


Figure 2. $\mathrm{V}_{\mathrm{OH}}$ Values

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